



FF1923 - Sn/Pb SOLDER BALLS
FFG1923 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	3.20	<i>~</i>	3.85	3
A ₁	0.40	0.50	0.60	
A ₂	1.10	<i>~</i>	1.50	
$\frac{D}{E}$	45.00 BASIC			
$\frac{D_1}{E_1}$	43.00 REF			
$\frac{e}{e}$	1.00 BASIC			
ϕ_b	0.50	0.60	0.70	
aaa	<i>~</i>	<i>~</i>	0.20	
bbb	<i>~</i>	<i>~</i>	0.25	
ddd	<i>~</i>	<i>~</i>	0.25	
eee	<i>~</i>	<i>~</i>	0.10	
M	44			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. ACTUAL SOLDER BALL COUNT = 1924

PK395_01_100709

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/20/09	1.0	Initial Xilinx release.

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